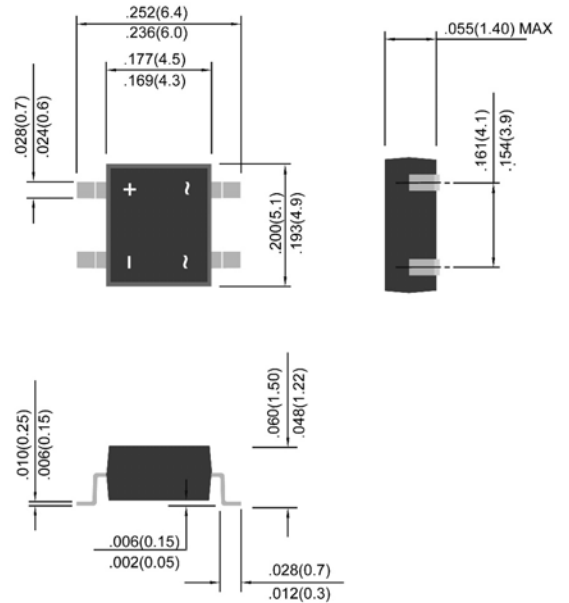




Features

- Glass passivated junction
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260 °C / 10 seconds / 0.375" (9.5mm) lead length at 5 lbs., (2.3 kg) tension
- Small size, simple installation
- High surge current capability

Thin Mini-Dip (THIN MD)



Dimensions in inches and (millimeters)

MECHANICAL DATA

- Case: Molded plastic body
- Terminal: Pure tin plated, lead free, Leads solderable per MIL-STD-202 Method 208
- Mounting position : as Marking

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

PARAMETER	SYMBOL	ABS2	ABS4	ABS6	ABS8	ABS10	UNIT
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average Forward Rectified Current On aluminum substrate	$I_{F(AV)}$	1					A
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	35					A
I^2t Rating for Fusing ($t < 8.3ms$)	I^2t	5.085					A ² S
Maximum Instantaneous Forward Voltage at 0.4A	V_F	0.95					V
Maximum DC Reverse Current at $T_A = 25^\circ C$ at Rated DC Blocking Voltage $T_A = 125^\circ C$	I_R	10 500					μA
Typical Thermal Resistance	$R_{\theta JL}$	25					°C/W
	$R_{\theta JA}$	62.5					
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150					°C

DEVICE CHARACTERISTICS

ABS2 THRU ABS10

FIG.1 MAXIMUM FORWARD CURRENT DERATING CURVE

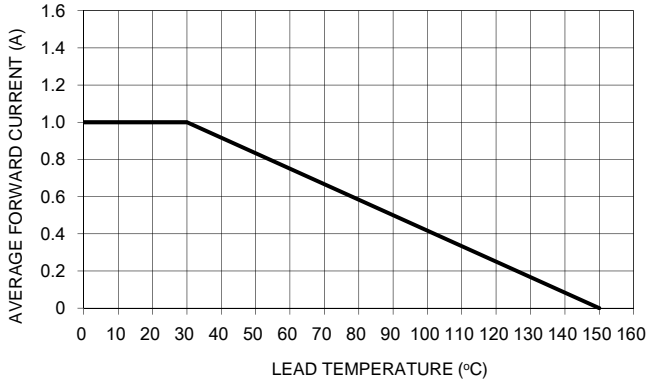


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

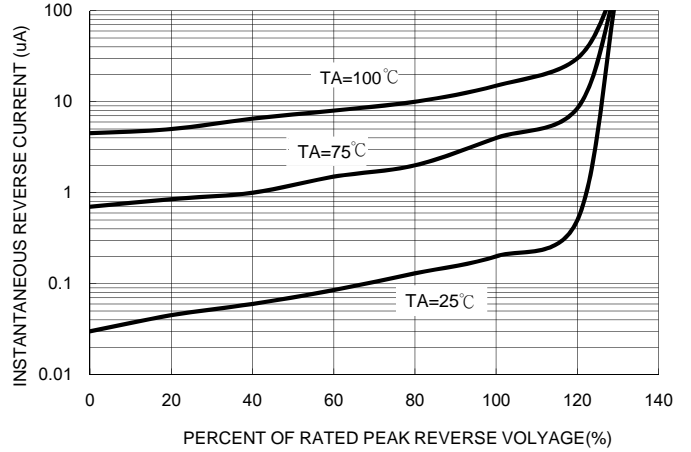


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

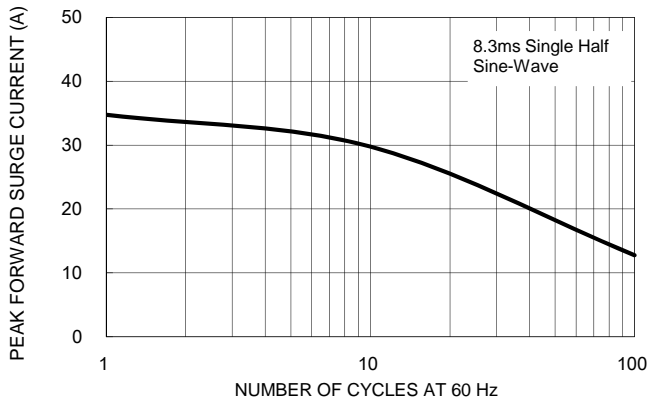


FIG. 4 TYPICAL JUNCTION CAPACITANCE

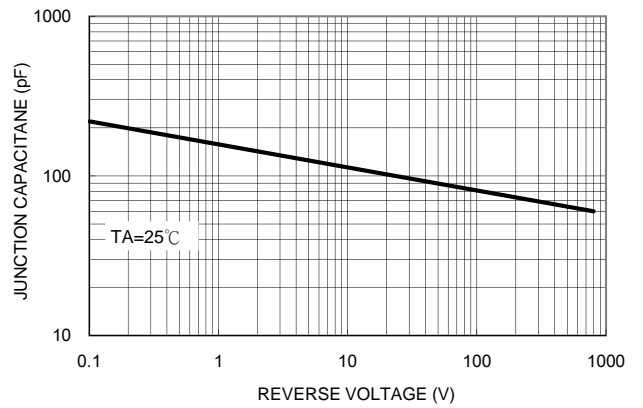


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

